Form PTO-14	149	•		Atty Do	cket No.	Serial No.			
U.S. Depar	tment	of Commerce,	Patent and 7	Grademark Office	BDG005-6	5	10/695	564	
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an	AA	4,971,930	11/1990	Fusaroli et al.	437	217			
pv	AB	5,530,282	06/1996	Tsuji	257	666			
pr	AC	6,512,219	01/2003	Webster et al.	250	208.1			
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BW	AA	5,440,231	08/1995	Sugai	324	158.1				
De D	AB	6,114,770	09/2000	Akram et al.	257	784				
P	AC	6,353,265	03/2002	Michii	257	777				
OU.	AD	6,369,595	04/2002	Farnworth et al.	324	755				
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av	AA	5,594,275	01/14/97	Kwon et al.	257	686		
Bes	AB	6,190,944	02/20/01	Choi	438	109		
por	AC	6,335,565	01/01/02	Miyamoto et al.	257	686		
m	AD	6,483,718	11/19/02	Hashimoto	361	803		
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	01/1992	•	Class	Subclass	Filing Date If Appropriate		
41,133		Yoshii et al.	357	80			
	08/1993	Mullen, III et al.	174	52.4			
94,303	02/28/95	Yamaji	361	749			
65,652	09/1997	Shimizu	438	127			
74,785	10/1997	Akram et al.	437	217			
44,827	04/28/98	Jeong et al.	257	686			
44,859	04/1998	Ouchida	257	668			
04,771	09/1998	McMahon et al.	174	255			
11,879	09/1998	Akram	257	723			
49,655	09/1999	Glenn	361	783			
13,877	01/2000	Degani et al.	174	264			
43,588	11/2000	Glenn	438	116			
59,770	12/2000	Tetaka et al.	438	112			
74,927	08/2001	Glenn	257	680			
Art (Inclu	uding Author	, Title, Date, P	ertinent	Pages, Etc	.)		
wley, "Soc 1998, pp.	ket Develop	ments for CSP and	l FBGA Pa	ckages," Ch	ip Scale Review,		
ster, "Soc 8, pp. 43-	ket Challen	ges for Chip-Scal	le Packag	es," Chip S	cale Review, May		
gai, "Chip iew, May 1	-Scale Pack 998, pp. 68	ages for Center-I	Pad Memor	y Devices,"	Chip Scale		
AR Vandevelde et al., "The PSGA, a Lead-Free CSP for High Performance & High Reliable Packaging," Proceedings of the 2001 International Symposium on Microelectronics, October 9, 2001, pp. 260-265.							
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Form PTO-14	449		Atty Docket No.	Serial No.				
U.S. Depar	tment	of Commerce, Patent and Trademark Office	BDG005-6	10/169556 J				
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	(Use	several sheets if necessary)	Cheng-Lien Chiang					
			Filing Date	Group Art Unit				
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*Examiner Initial		Other Art (Including Author, Title, D	ate, Pertinent Pages	, Etc.)				
an/	AA	U.S. Application Serial No. 09/865,367, "Semiconductor Chip Assembly With Simultaterminal and Connection Joint"	filed May 24, 2001, eaneously Electroplate	entitled ed Contact				
	АВ	U.S. Application Serial No. 09/864,555, "Semiconductor Chip Assembly with Simulta Contact Terminal and Connection Joint"	filed May 24, 2001, eaneously Electroless	entitled ly Plated				
	AC U.S. Application Serial No. 09/864,773, filed May 24, 2001, entitled "Semiconductor Chip Assembly With Ball Bond Connection Joint"							
	AD U.S. Application Serial No. 09/878,649 filed June 11, 2001, entitled "Metho of Making a Semiconductor Chip Assembly with a Conductive Trace Subtractively Formed Before and After Chip Attachment"							
	AE	U.S. Application Serial No. 09/878,626 for Connecting a Conductive Trace to a Serial No. 09/878,626 for Connecting a Conductive Trace to a Serial No. 09/878,626 for Connecting a Conductive Trace to a Serial No. 09/878,626 for Connecting a Conductive Trace to a Serial No. 09/878,626 for Connecting a Conductive Trace to a Serial No. 09/878,626 for Connecting a Conductive Trace to a Serial No. 09/878,626 for Connecting a Conductive Trace to a Serial No. 09/878,626 for Connecting a Conductive Trace to a Serial No. 09/878,626 for Connecting a Conductive Trace to a Serial No. 09/878,626 for Connecting a Conductive Trace to a Serial No. 09/878,626 for Connecting No	iled June 11, 2001, omiconductor Chip"	entitled "Method				
	AF	U.S. Application Serial No. 09/917,339 for Connecting a Bumped Compliant Conduct	iled July 27, 2001, o	entitled "Method onductor Chip"				
	AG	U.S. Application Serial No. 09/927,216 f: "Semiconductor Chip Assembly with Harden	iled August 10, 2001, ed Connection Joint"	, entitled				
	AH	U.S. Application Serial No. 09/939,140 f: "Semiconductor Chip Assembly with Interlo	iled August 24, 2001, ocked Conductive Trac	, entitled ce"				
	AI	U.S. Application Serial No. 09/962,754 for "Method of Connecting a Conductive Trace Semiconductor Chip"	iled September 24, 20 and an Insulative Ba	001, entitled ase to a				
	ΑJ	U.S. Application Serial No. 09/972,796 f: "Method of Connecting a Bumped Compliant Base to a Semiconductor Chip"	iled October 6, 2001, Conductive Trace and	, entitled d an Insulative				
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U.S. Depart	tment	of Commerce,	Patent and T	rademark Office	BDG005-6	5	10/69	5564
I	NFORM	ATION DISCI	OSURE STAT	TEMENT	Applicar	it		
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*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing I	
ou/	AA	4,706,166	11/10/87	Go	361	403		<u> </u>
	AB	4,807,021	02/21/89	Okumura	357	75		
	AC	4,897,708	01/30/90	Clements	357	65		
	AD	4,954,875	09/04/90	Clements	357	75		
	AE	4,984,358	01/15/91	Nelson'	29	830		
	AF	4,996,583	02/26/91	Hatada	357	70		
	AG	5,049,979	09/17/91	Hashemi et al.	357	75		·
	АН	5,104,820	04/14/92	Go, deceased et al.	437	51	<del></del>	
	AI	5,138,438	08/11/92	Masayuki et al.	357	75		
	AJ	5,332,922	07/26/94	Oguchi et al.	257	723		
	AK	5,484,959	01/16/96	Burns	174	524		
	AL	5,514,907	05/07/96	Moshayedi	257	723		
or	MA	5,625,221	04/29/97	Kim et al.	257	686		
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on	AP	U.S. Applica "Three-Dimen	tion Serial sional Stack	No. 09/917,358, f ed Semiconductor	iled Jul Package"	y 27, 2001,	entitled	l
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as I	AA	5,804,874	09/08/98	An et al.	257	676	-		
	AB	5,854,507	12/29/98	Miremadi et al.	257	686			
	AC	5,861,666	01/19/99	Bellaar	257	686			
	AD	5,910,685	06/08/99	Watanabe et al.	257	777			
	AE	5,973,393	10/26/99	Chia et al.	257	690			
	AF	6,072,233	06/06/00	Corisis et al.	257	686			
	AG	6,124,633	09/26/00	Vindasius et al.	257	685			
	AH	6,231,364	05/15/01	Liu	439	326			
on	AI	6,233,154	05/15/01	Farnworth et al.	361	752			
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<u>h</u>	AA	5,149,958	09/1992	Hallenbeck et al.	250	216			
	AB	5,264,714	11/1993	Nakaya et al.	257	78	<u> </u>		
	AC	5,405,809	04/1995	Nakamura et al.	437	209			
	AD	5,834,835	11/1998	Maekawa	257	680			
	AE	5,834,843	11/1998	Mori et al.	257	723			
	AF	5,859,471	01/1999	Kuraishi et al.	257	666			
	AG	5,893,723	04/1999	Yamanaka	438	65			
on/	AH	6,265,770	07/2001	Uchiyama	257	698			
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PW	AA	3,627,901	12/1971	Нарр	174	52 PE			
	AB	3,678,385	07/1972	Bruner	324	158 F			
	AC	3,930,114	12/1975	Hodge	174	52 FP			
	ΆD	4,506,238	03/1985	Endoh et al.	333	138			
	AE	5,157,480	10/1992	McShane et al.	357	74			
	AF	5,207,102	05/1993	Takahashi et al.	73	727		_	
	AG	5,436,500	07/1995	Park et al.	257	696	<u> </u>		
	АН	5,677,566	10/1997	King et al.	257	666	-		
	AI	5,866,939	02/1999	Shin et al.	257	666		··	
	AJ	5,894,107	04/1999	Lee et al.	174	52.2			
	AK	5,951,804	09/1999	Kweon et al.	156	244.12			
	AL	6,114,770	09/2000	Akram et al.	257	784			
	AM	6,130,116	10/2000	Smith et al.	438	127			
	AN	6,232,152	05/2001	DiStefano et al.	438	124			
	AO	6,297,543	10/2001	Hong et al.	257	666			
	AP	6,303,997	10/2001	Lee	257	778		-	
	AQ	6,326,700	12/2001	Bai et al.	257	790			
	AR	6,445,077	09/2002	Choi et al.	257	786			
	AS	6,455,356	09/2002	Glenn et al.	438	123			
ON .	AT	6,468,836	10/2002	DiStefano et al.	438	128			
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m	AA	6,001,671	12/1999	Fjelstad	438	112		
m	AB	6,025,650	02/2000	Tsuji et al.	257	786		
m	AC	6,281,568	08/2001	Glenn et al.	257	684		
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